

Special Issue

Engineering Soft–Rigid Interfaces Through 3D Printing: Challenges, Opportunities, and Advances in Materials, Characterization, and Applications

Message from the Guest Editor

This Special Issue will focus on the latest advances in the fabrication, characterization, and application of 3D-printed soft–rigid interface materials. We aim to explore a wide range of materials, including polymers, metals, and ceramics, in addition to their combinations, using diverse 3D printing methods such as extrusion-based printing, selective laser melting (SLM), powder bed fusion, fused deposition modeling (FDM), stereolithography (SLA), digital light processing (DLP), multi-jet fusion (MJF), selective laser sintering (SLS), direct ink writing (DIW), laminated object manufacturing (LOM), and electron beam melting (EBM). The goal is to provide insights into optimizing the mechanical properties of these materials, addressing key challenges, and exploring their potential in innovative applications.

Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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